

**Eliminate Mechanical Fasteners During Assembly With Liqui-Bond™ SA 2000.**

**Liqui-Bond SA 2000 (One-Part)**

- High thermal conductivity: 2.0 W/m-K
- Eliminates need for mechanical fasteners
- One-part formulation for easy dispensing
- Mechanical and chemical stability
- Maintains structural bond in severe-environment applications
- Heat cure

New high performance Liqui-Bond SA 2000 thermally conductive liquid adhesive cures fast and quickly conforms to the shape of surface components to increase the contact area. This eliminates the need for mechanical fasteners thus reducing material and labor costs as well as application complexity.

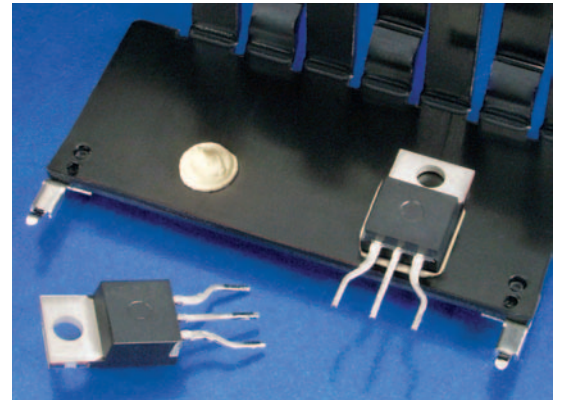
**Clean, simple, and precise application.**

Because it's a liquid, Liqui-Bond SA 2000 can be used with an automated dispensing system for fast, precise placement. The material's one-part, stay-in-place formulation dispenses easily and eliminates flow after being dispensed for cleaner, easier application.

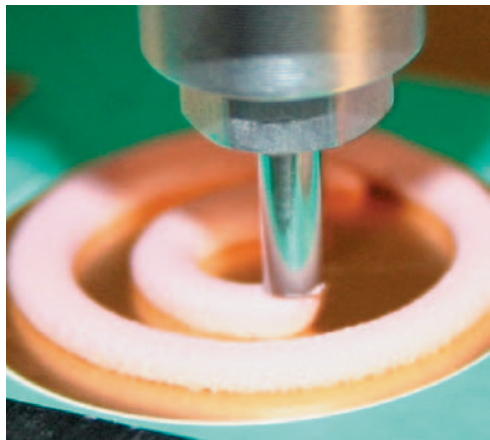
**Outstanding performance.**

Liqui-Bond SA 2000 provides extremely high thermal performance, with dielectric strength of 250 Volts per mil and thermal conductivity of 2 W/m-K. Liqui-Bond SA 2000's low post-cure modulus ensures that the CTE stresses associated with thermal cycling minimize the stresses transferred to pressure-sensitive components.

**For a FREE sample packet, call 1.800.347.4572 or visit [www.bergquistcompany.com/liquibond](http://www.bergquistcompany.com/liquibond)**



*Liqui-Bond SA 2000. A one-part formulation featuring a fast cure rate for use in power supplies, automotive electronics control modules, motor controls, discrete devices and a variety of other applications.*



**Soft, Form-In-Place Elastomer Offers High Performance For Coupling "Hot" Electronic Components On PC Boards.**

**Gap Filler 2000 (Two-Part)**

- Thermal conductivity: 2.0 W/m-K
- Ultra-conforming for fragile and low-stress applications
- Ambient and accelerated cure schedules
- 100% solids – no cure by-products
- Excellent low and high temperature mechanical and chemical stability

**Clean and simple automated application.**

Gap Filler 2000 flows under pressure like a grease, an ideal fit for automated dispensing systems. The material is made of 100% solids, so as it cures there are no cure by-products to contend with. Once fully cured at ambient or elevated temperature, Gap Filler 2000 will not pump from the interface after thermal cycling. And, unlike grease, the cured product is dry to the touch resulting in a lot less mess.

**Ideal for fragile and low-stress applications.**

Gap Filler 2000's ultra-conforming properties provide infinite-thickness coverage of uneven board topography with little or no stress during displacement and assembly. This eliminates the need for specific pad thickness and die-cut shapes for individual applications thereby reducing cost and simplifying application.

**Superior thermal performance.**

Best of all, high performance Gap Filler 2000 provides thermal conductivity of 2.0 W/mK – ideal for coupling "hot" electronic components mounted on PC boards with an adjacent metal case or heat sink.

**For a FREE sample packet, call 1.800.347.4572 or visit**

**[www.bergquistcompany.com/gapfiller](http://www.bergquistcompany.com/gapfiller)**



**OUR NEW TACK TO SUPERIOR DISPENSING.**

**New Sil-Pad® 1500ST Delivers Trouble-free, High Throughput Dispensing With Unequaled Thermal Performance.**



**Clean, consistent handling for precise auto-dispensing.**

Bergquist's new Sil-Pad 1500ST (soft tack) high performance thermal interface material is designed specifically for use in high-volume auto-dispensing/auto-placement applications. Sil-Pad 1500ST's inherent natural tack keeps the material

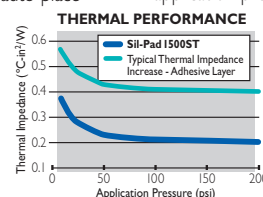
on the carrier liner during converting, yet consistently and cleanly releases during dispensing. This tack characteristic keeps the material securely on the target surface with no need for additional adhesive layers.

**A superior performance from start to finish.**

You'll be amazed by Sil-Pad 1500ST's thermal performance. Typically, adhesive-coated materials add thickness, thereby decreasing thermal performance. With no adhesive to hold it back, Sil-Pad 1500ST cuts thermal impedance to 0.23° C-in<sup>2</sup>/W at an application pressure of just 50 psi. It can even be easily repositioned without delaminating, losing adhesion strength or sacrificing thermal performance.

**FREE sample roll of Sil-Pad 1500ST.**

Visit our web site or call today to qualify for your FREE sample roll.



Call **1.800.347.4572** or visit **[www.bergquistcompany.com/throughput](http://www.bergquistcompany.com/throughput)**

Get your FREE Sil-Pad 1500ST roll.



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